

Title (en)  
Connector with integrated PCB assembly

Title (de)  
Steckverbinder mit integrierter Leiterplattenanordnung

Title (fr)  
Connecteur avec assemblage intégré de circuit imprimé

Publication  
**EP 0852414 A3 19991027 (EN)**

Application  
**EP 97122940 A 19971229**

Priority  
• US 3469097 P 19970107  
• US 78474397 A 19970116

Abstract (en)  
[origin: EP0852414A2] Shielded pair or twinax connectors constructed from printed circuit board modules (30) are disclosed. The printed circuit boards (31) include mirror-image pairs of terminal conductors (32), with appropriate electrical shielding (33,36,38). The connectors can be board-mounted or cable mounted. The cable connectors can be constructed from a PCB assembly having a cover (100) with a retention structure (102) for a cable or other flexible conductor.

IPC 1-7  
**H01R 23/68**; **H01R 13/658**

IPC 8 full level  
**H01R 13/648** (2006.01); **H01R 13/658** (2011.01)

CPC (source: EP)  
**H01R 13/6587** (2013.01); **H01R 13/6658** (2013.01)

Citation (search report)  
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Designated contracting state (EPC)  
AT BE CH DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE

DOCDB simple family (publication)  
**EP 0852414 A2 19980708**; **EP 0852414 A3 19991027**; **EP 0852414 B1 20041124**; CA 2225151 A1 19980707; CA 2225151 C 20010227; CN 1190807 A 19980819; DE 69731719 D1 20041230; DE 69731719 T2 20050901; JP 4565673 B2 20101020; JP H10270133 A 19981009; SG 71746 A1 20000418; TW 385579 B 20000321

DOCDB simple family (application)  
**EP 97122940 A 19971229**; CA 2225151 A 19971217; CN 98104204 A 19980106; DE 69731719 T 19971229; JP 177998 A 19980107; SG 1998000014 A 19980102; TW 87100146 A 19980107